

PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

EPAS ID: PAT2652299

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
Name		Execution Date
HYUN JIN LEE		11/06/2013
RECEIVING PARTY DATA		
Name:	SK hynix Inc.	
Street Address:	2091, Gyeongchung-daero, Bubal-eub	
City:	Icheon	
State/Country:	KOREA, REPUBLIC OF	
Postal Code:	467-734	
PROPERTY NUMBERS Total: 1		
Property Type	Number	
Application Number:	14097008	
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ATTORNEY DOCKET NUMBER:	K100BK-042300US	
NAME OF SUBMITTER:	STEVE Y. CHO	
Signature:	/Steve Y. Cho/	
Date:	12/17/2013	
Total Attachments: 1 source=2013_12_17_ASSGMT_K100BK-042300US#page1.tif		

OP \$40.00 14097008

ASSIGNMENT OF PATENT APPLICATION

WHEREAS, the below named individual(s), hereinafter referred to as "Assignors," are the inventor(s) of the invention described and set forth in the below-identified application for United States Letters Patent:

Title of Invention: SEMICONDUCTOR DEVICE AND METHOD
FOR FORMING THE SAME

Filing Date: December 04, 2013

Application No.: 14/097,008

WHEREAS, SK hynix, Inc. of 2091, Gyeongchung-daero, Bubal-eub, Icheon-si, Gyeonggi-do 467-734, Republic of Korea, hereinafter referred to as "ASSIGNEE," is desirous of acquiring ASSIGNORS' interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignors, Assignors have sold, assigned and transferred, and by these presents do sell, assign and transfer unto the said Assignees, and Assignees' successors and assigns, all their right, title and interest in and to the said invention and application including any corresponding foreign application, and in and to any Letters Patent which may hereafter be granted on the same in the United States and any corresponding foreign application, the said interest to be held and enjoyed by said Assignees as fully and exclusively as it would have been held and enjoyed by said Assignors had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignors further agree that they will, without charge to Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in Assignee, or Assignee's successors and assigns.

Assignors hereby authorize and request AMPACC Law Group, PLLC, 6100 219th Street SW, Suite 580, Mountlake Terrace, WA 98043, to insert herein above the application number and filing date of said application when known.

IN TESTIMONY WHEREOF, Assignors have signed their names on the dates indicated.

November 6, 2013
Date:


Name: Hyun Jin LEE